



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar

Title: PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES

Docket No.: 303.603US1

Serial No.: 09/382,929

Filed: August 25, 1999

Due Date: N/A

Examiner: Thanh V. Tran

Group Art Unit: 2814

Commissioner for Patents
Washington, D.C. 20231

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ A Supplemental Information Disclosure Statement (1 pgs.), Form 1449 (1 pgs.), and copies of 6 cited references.
- ☒ A Communication Concerning Co-Pending Applications (1 pg.).

Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

By: Danny J. Padya
Atty: Danny J. Padya
Reg. No. 35,635

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 20 day of November, 2001.

Gina M. Uphus

Name

Signature

Customer Number 21186

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P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

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PATENT

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant further request that a copy of the 1449 form, initialled by the Examiner to indicate that all listed citations have been considered, be returned with the next official communication.

Under 37 C.F.R. §1.97(b)(3), it is believed that no fee or certificate is required with this Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge any additional fees or credit any overpayment to Account No. 19-0743.

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

PAUL A. FARRAR

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
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Date

November 20, 2001

By

Danny J. Padys

Danny J. Padys
Reg. No. 35,635

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Gina M. Uphus

Name

Signature

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PATENT

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Applicant: Paul A. Farrar

Examiner: Thanh V. Tran

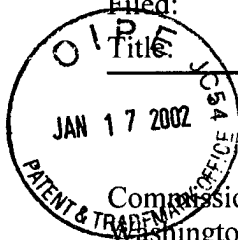
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COMMUNICATION CONCERNING CO-PENDING APPLICATION(S)

Applicant would like to bring to the Examiner's attention the following related co-pending application(s) in the above-identified patent application:

<u>Serial No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/507,964	02/22/2000	00303.681US1	POLYNORBORNENE FOAM INSULATION FOR INTEGRATED CIRCUITS
09/640,149	08/16/2000	N/A	MICROELECTRONIC DEVICE PACKAGE WITH CONDUCTIVE ELEMENTS AND ASSOCIATED METHOD OF MANUFACTURE
09/894,528	06/27/2001	N/A	MICROELECTRONIC DEVICE PACKAGE FILLED WITH LIQUID OR PRESSURIZED GAS AND ASSOCIATED METHOD OF MANUFACTURE

Respectfully submitted,

PAUL A. FARRAR

By Applicant's Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
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Date November 20, 2001

By

Danny L. Padys

Danny L. Padys
Reg. No. 35,635

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 22 day of November, 2001.

Gina M. Uphus

Name

Signature

Gina M. Uphus